

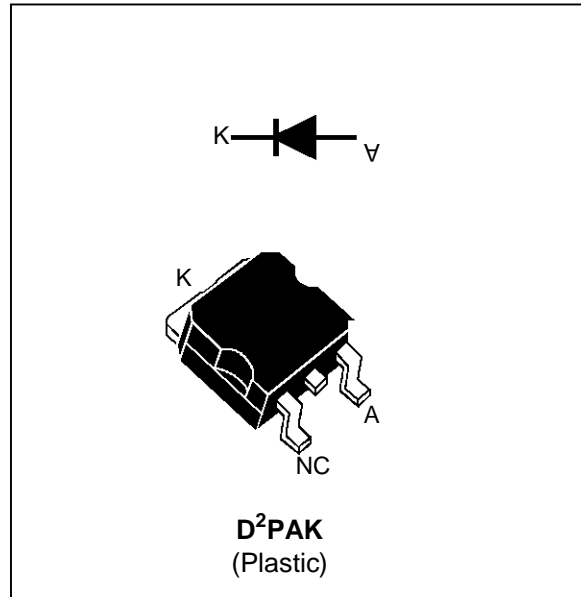
(CRT HORIZONTAL DEFLECTION) HIGH VOLTAGE DAMPER DIODE

FEATURES

- HIGH BREAKDOWN VOLTAGE CAPABILITY
- HIGH FREQUENCY OPERATION
- SPECIFIED TURN ON SWITCHING CHARACTERISTICS
- TYPICAL TOTAL LOSSES : 3.5W
($I_{Fpeak} = 6\text{ A}$, $F = 56\text{ kHz}$)
- SUITABLE WITH **BUH** TRANSISTORS SERIES
- SMD PACKAGE

DESCRIPTION

High voltage diode especially designed for horizontal deflection stage in standard and high resolution displays for TV's and monitors.
This device is packaged in D²PAK.



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
$I_{F(RMS)}$	RMS forward current		15	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	$T_c = 130^\circ\text{C}$	6	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ms}$ sinusoidal	100	A
T_{stg} T_j	Storage and junction temperature range		- 40 to + 150 - 40 to + 150	$^\circ\text{C}$ $^\circ\text{C}$

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	1500	V
V_{RWM}	Reverse working voltage	1350	V

DTV32G-1500B

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth (j-c)	Junction to case	2	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I _R *	T _j = 25°C	V _R = V _{RWM}			200	μA
	T _j = 100°C				1	mA
V _F **	T _j = 25°C	I _F = 6 A			1.5	V
	T _j = 100°C	I _F = 6 A			1.4	

Pulse test : * tp = 5 ms, duty cycle < 2 %

** tp = 380 μs, duty cycle < 2 %

RECOVERY CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
trr (1)	T _j = 25°C	I _F = 1 A V _R = 30 V	dI _F /dt = -50 A/μs			175	ns
trr (1)	T _j = 25°C		dI _F /dt = -15 A/μs		250		ns
trr	T _j = 25°C	I _F = 100mA	I _R = 100mA		140		ns

TURN ON SWITCHING CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
t _{FR} (2)	T _j = 100°C	I _F = 6 A	dI _F /dt = 80 A/μs		0.6		μs
V _{FP} (2)		V _{FR} = 2 V				39	V

(1) Test following Jedec Standard

(2) Test representative of the application

To evaluate the conduction losses use the following equations :

$$V_F = 1.2 + 0.034 I_F$$

$$P = 1.2 \times I_{F(AV)} + 0.034 \times I_{F(RMS)}^2$$

Fig.1 : Average forward power dissipation versus average forward current.

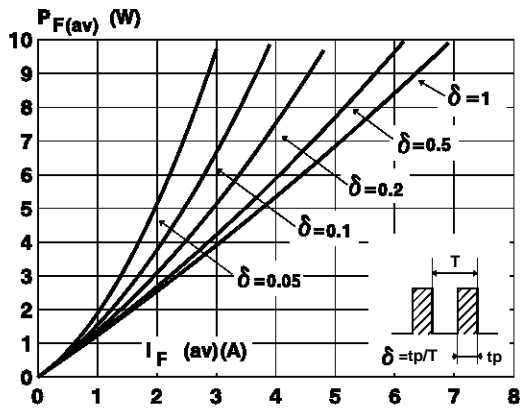


Fig. 2 : Peak current versus form factor.

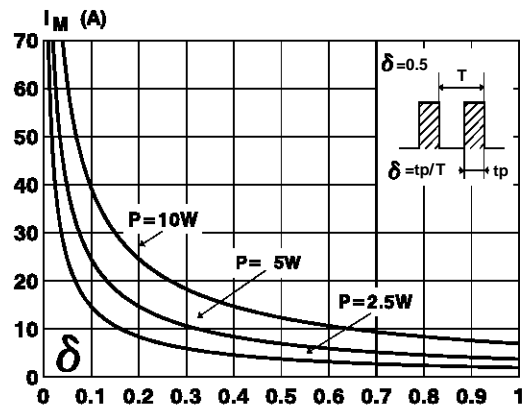


Fig. 3 : Average current versus ambient temperature. (duty cycle : 0.5)

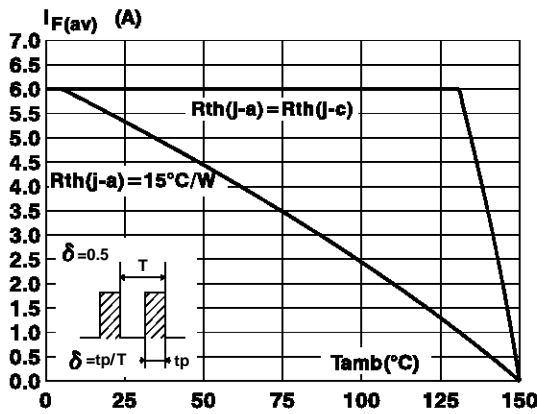


Fig. 4 : Non repetitive surge peak forward current versus overload duration. (Maximum values)

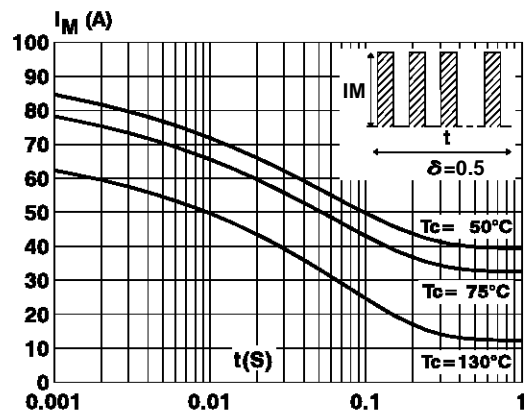


Fig.5 : Relative variation of thermal transient impedance junction to case versus pulse duration.

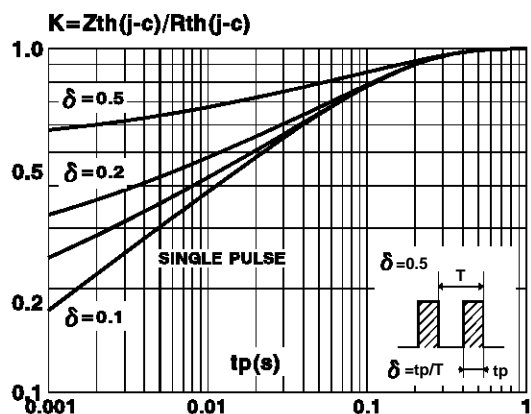


Fig.6 : Forward voltage drop versus forward current. (Maximum values)

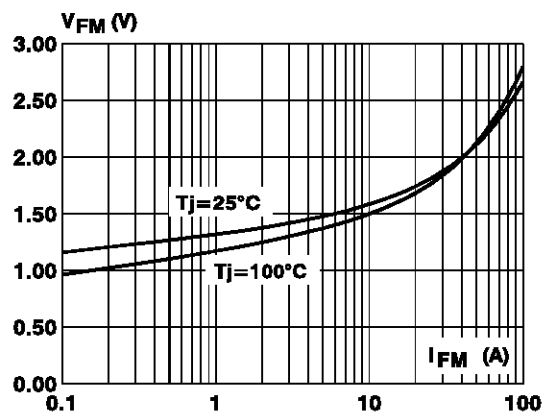


Fig.7 : Junction capacitance versus reverse voltage applied. (Typical values)

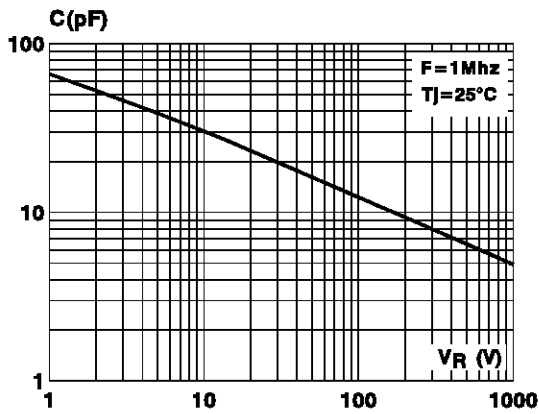


Fig.8 : Recovery charge versus di_F/dt .

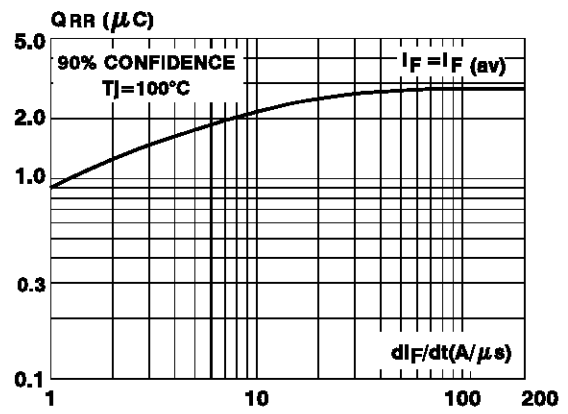


Fig.9 : Peak reverse current versus di_F/dt .

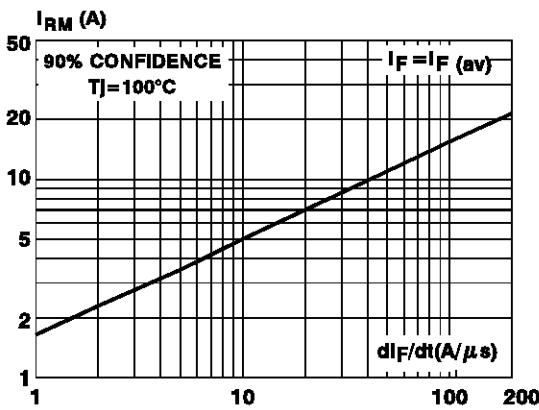


Fig.10 : Dynamic parameters versus junction temperature.

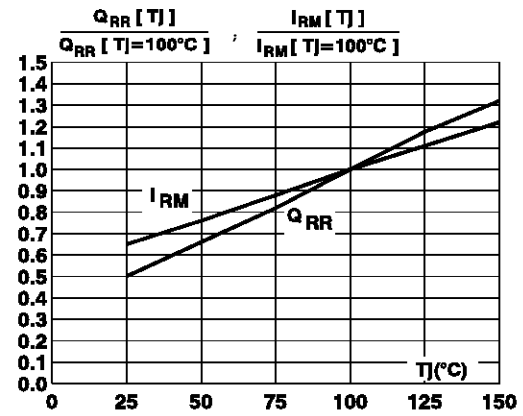


Fig.11 : Recovery time versus di_F/dt .

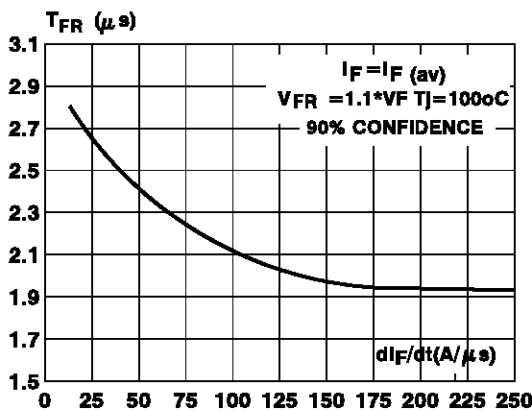
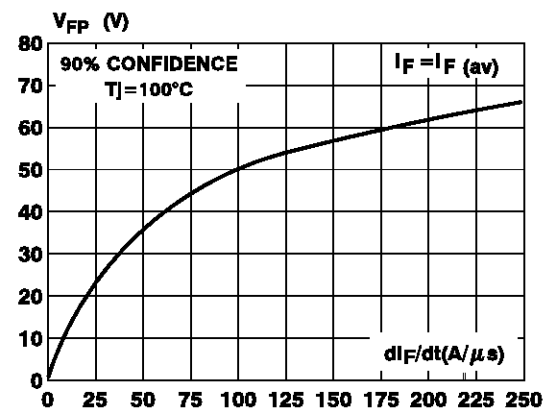
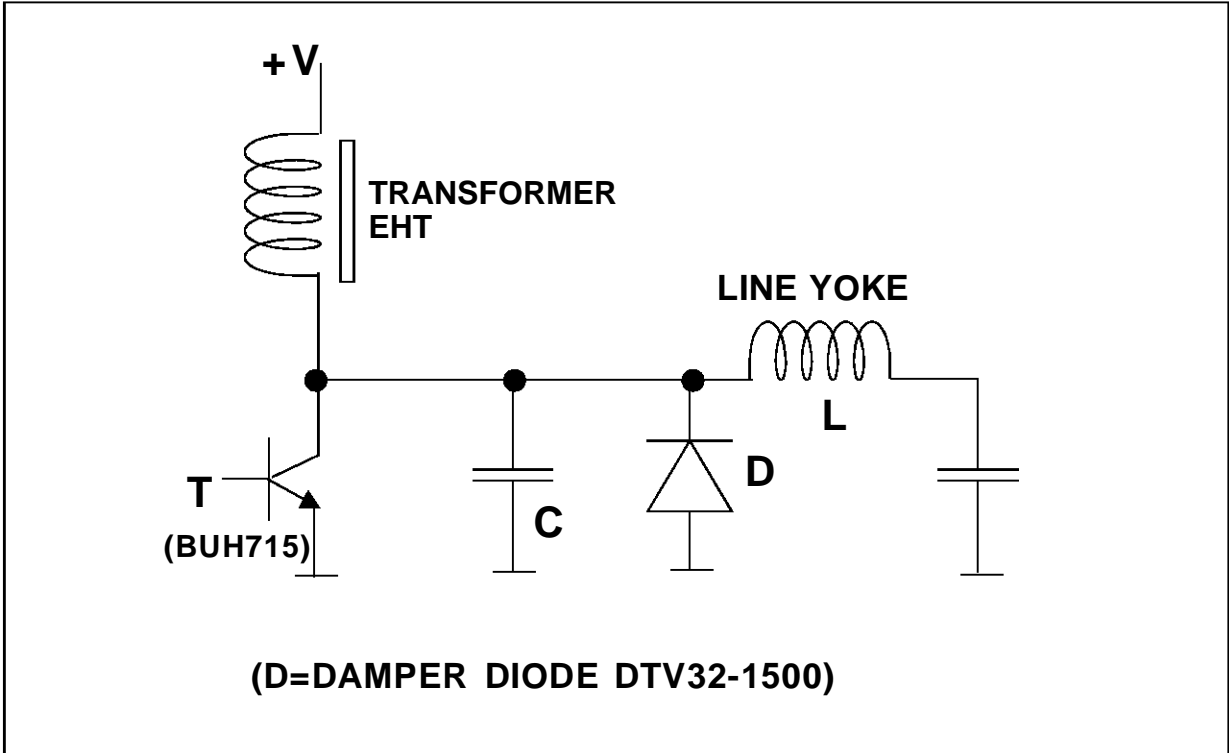


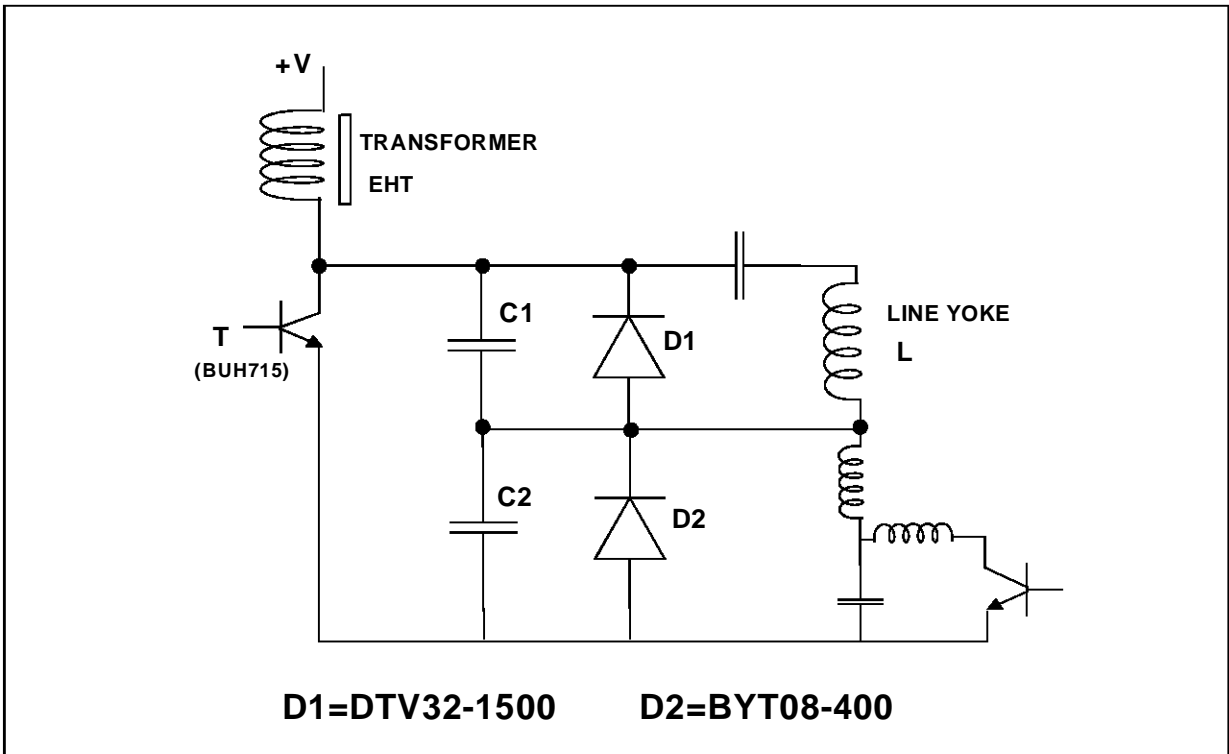
Fig.12 : Peak forward voltage versus di_F/dt .



BASIC HORIZONTAL DEFLECTION CIRCUIT

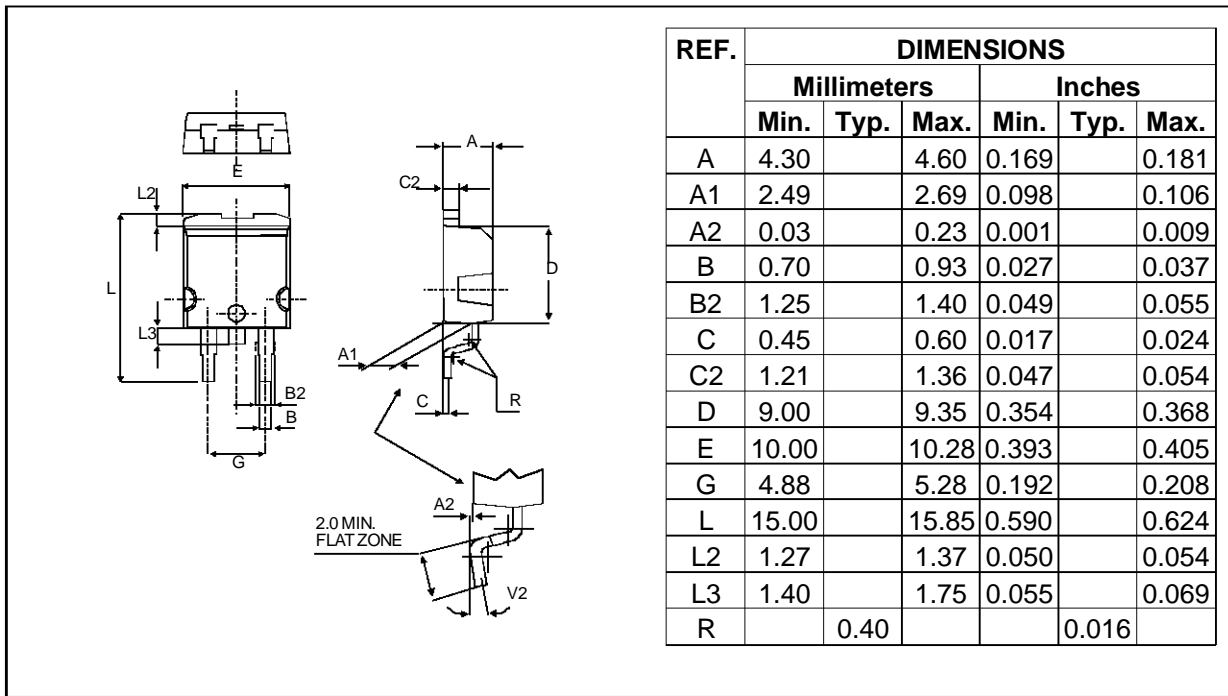


BASIC E-W DIODE MODULATOR CIRCUIT



PACKAGE MECHANICAL DATA

D²PAK (Plastic)



Cooling method : C
 Marking : Type number
 Weight : 1.8 g

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